

Michael Lane

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/10615770/publications.pdf>

Version: 2024-02-01

12
papers

633
citations

1163117

8
h-index

1281871

11
g-index

12
all docs

12
docs citations

12
times ranked

512
citing authors

#	ARTICLE	IF	CITATIONS
1	Adhesion and reliability of copper interconnects with Ta and TaN barrier layers. Journal of Materials Research, 2000, 15, 203-211.	2.6	165
2	Plasticity contributions to interface adhesion in thin-film interconnect structures. Journal of Materials Research, 2000, 15, 2758-2769.	2.6	164
3	Annealing-induced interfacial toughening using a molecular nanolayer. Nature, 2007, 447, 299-302.	27.8	118
4	Interface Fracture. Annual Review of Materials Research, 2003, 33, 29-54.	9.3	92
5	Adhesion Measurement of Interfaces in Multilayer Interconnect Structures. Materials Research Society Symposia Proceedings, 1997, 473, 3.	0.1	29
6	Interfacial Relationships in Microelectronic Devices. Materials Research Society Symposia Proceedings, 2003, 766, 911.	0.1	19
7	Gold-titania interface toughening and thermal conductance enhancement using an organophosphonate nanolayer. Applied Physics Letters, 2013, 102, 201605.	3.3	15
8	Progressive Debonding of Multilayer Interconnect Structures. Materials Research Society Symposia Proceedings, 1997, 473, 21.	0.1	12
9	Subcritical Debonding of Multilayer Interconnect Structures: Temperature and Humidity Effects. Materials Research Society Symposia Proceedings, 1999, 563, 251.	0.1	9
10	Atomistic fracture energy partitioning at a metal-ceramic interface using a nanomolecular monolayer. Physical Review B, 2011, 83, .	3.2	8
11	Effect of Nitrogen Content on Interfacial Adhesion of the Ta/SiO ₂ Interface. Materials Research Society Symposia Proceedings, 1999, 564, 281.	0.1	2
12	Mechanical Scaling Trends and Methods to Improve Reliability of Packaged Interconnect Structures. Materials Research Society Symposia Proceedings, 2009, 1158, 1.	0.1	0